1	mp	Time stamp	DB	Search Text	Hits	L Number
100 ((dress\$3 clean\$3 condition\$3) with (pad cloth)) same (CMP "chemical mechanical") (((dress\$3 clean\$3 condition\$3) with (pad cloth)) same (CMP "chemical mechanical") uspat ((dress\$3 clean\$3 condition\$3) with (pad cloth)) same (CMP "chemical mechanical") uspat (condition\$3 dress\$3 clean\$3)) uspat (condition\$3 dress\$3 clean\$3) uspat (condition\$3 dress\$3 clean\$3) uspat (condition\$3) (condition\$3)	07 10:48	2004/01/07	USPAT			
Cloth) same (CMP "chemical mechanical")	07 12:56	2004/01/07		(/drose\$3 clear\$3 condition\$3) with (pad		_
114				cloth) same (CMP "chemical mechanical")	090	2
Coloth) same (CMP "chemical mechanical") and ((analy\$3 monitor\$3 test\$3) with (condition\$3 dress\$3 clean\$3))	07 12:57	2004/01/07	USPAT	(//drose\$3 cloan\$3 condition\$3) with (pad	114	_
and ((analy\$3 monitor\$3 test\$3) with (condition\$3 dress\$3 clean\$3)) 156/345.12 156/345.13 156/345.16 13915 (polishing planariz\$5) same (grind\$3				(((dlessys cleanys condicionys) with (page 1))	114	3
Condition\$3 dress\$3 clean\$3)				and //analys3 monitors3 tests3) with		
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13915 (polishing planariz\$5) same (grind\$3 USPAT 2003/09/04 10 condition\$3 ("chemical mechanical" adj(polishing planariz\$5) same (grind\$3 condition\$3)) (("chemical mechanical" adj(polishing planariz\$5) same (grind\$3 condition\$3)) same ((analyz\$5) same (grind\$3 condition\$3)) same ((ucopper) ("ammonium citrate" "nitric acid") same ((ucopper) (("ammonium citrate" "nitric acid") same ((ucopper) and (polish\$3 abrad\$3) planariz\$5) chopra-dinesh.in. meikle-scott.in. USPAT	04 10:29	2003/09/04	USPAT	156/245 12 156/245 13 156/345 16	274	
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1270	ļ				13915	-
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or "pressure releasing")	104 14 22	0000 100 10		or "pressure releasing")		
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143 (((drv plasma) adj5 (polish\$3 abrad\$3 EPO; JPO; 2003/09/04 1	/04 14:50	2003/09/04		(((dry plasma) adj5 (polish\$3 abrad\$3	143	-
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_ 21 (134/113 134/104.1) and (dress\$3 grind\$3 USPAT 2003/09/05 1	/05 14:41	2003/09/0	USPAT	(134/113 134/104.1) and (dress\$3 grind\$3		-
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